

Integrated Device Technology, Inc. 6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

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PCN #: A1709-04	DATE: 25- 0	Oct-2017	MEANS OF DISTINGUISHING CHANGED DEVICES:		
Product Affected: VFQFPN-28 (Refer to Attachment II for th	e affected part nu	mbers)	☐ Product M ■ Back Mark □ Date Code □ Other	Lot # will have "RC" prefix fo	e: r ASECL, Taiwan
Date Effective: 25-Jan-2018					
Contact: IDT PCN DESK			Attachment:	Yes	☐ No
E-mail: pcndesk@idt.com			Samplee	ase contact your local	sales representative for
DESCRIPTION AND PURPOSE OF	CHANGE:				
 □ Die Technology □ Wafer Fabrication Process □ Assembly Process □ Equipment □ Material □ Testing ■ Manufacturing Site □ Data Sheet □ Other 		bly facility	for parts that a	are currently assemble	ASECL, Taiwan as an ed at UTL, Thailand.
RELIABILITY/QUALIFICATION S Refer to qualification data shown in Att					
CUSTOMER ACKNOWLEDGMEN	Г OF RECEIPT:	:			
IDT records indicate that you require w to grant approval or request additional i it will be assumed that this change is ac IDT reserves the right to ship either ver on the earlier version has been depleted	nformation. If ID' ceptable. sion manufactured	T does not	receive acknow	wledgement within 30	days of this notice
Customer:			Approva	l for shipments pr	rior to effective date.
Name/Date:		E-	Mail Address:		
Title:		Ph	one#/Fax#:		
CUSTOMER COMMENTS:					
IDT ACKNOWLEDGMENT OF REC	CEIPT:				
RECD. BY:			DATE:		

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ATTACHMENT I - PCN #: A1709-04

PCN Type: Manufacturing Site - Alternate Assembly Location

Data Sheet Change: None

No change in moisture sensitivity level (MSL)

Detail Of Change:

This notification is to advise our customers that IDT is adding ASECL, Taiwan as an alternate assembly facility for parts that are currently assembled at UTL, Thailand.

The material set details of the current and alternate assembly location is as shown in Table 1.

There is no change to the moisture performance.

Table 1: Assembly Material Sets for The Existing and Alternate Assembly Location

	Existing Assembly (UTL, Thailand)	Alternate Assembly (ASECL, Taiwan)	
Die Attach	8600	EN4900G	
Bond Wire	Copper Wire	Copper Wire	
Mold Compound	G700LTD	G700LA	

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ATTACHMENT I - PCN #: A1709-04

Qualification Information and Qualification Data:

Affected Packages: VFQFPN-28

Assembly Material: Shown on page 2 of this attachment.

Qual Plan & Results: Tests are in accordance with JEDEC47 recommended tests.

Qualification Vehicle: VFQFPN-36

Tost Description	Test Method	Test Results (Rej / SS)			
Test Description	Test Wiethou	Lot 1	Lot 2	Lot 3	
* Temperature Cycling (-55°C to 125°C, 700 cycles)	JESD22-A104	0/25	0/25	0/25	
* HAST - biased (130 °C/85% RH, 96 Hrs)	JESD22-A110	0/25	0/25	0/25	
High Temperature Storage Bake (150°C, 1000 Hrs)	JESD22-A103	0/25	0/25	0/25	
Ball Shear Test	JESD22-B116	0/5	0/5	0/5	
Bond Pull Test	MIL-STD-883 (Method 2011)	0/5	0/5	0/5	
X Ray	IDT Spec. MAC-3012	0/45	0/45	0/45	
Moisture Sensitivity Level, MSL	J-STD-20 / MSL 1, 260 °C	0/25	0/25	0/25	

^{*} Tests were subjected to Preconditioning per JESD22-A113 prior to stress test

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ATTACHMENT II - PCN #: A1709-04

Part Number	Part Number	Part Number	Part Number
F1451NKGI	F1456NKGI	F1455NKGI8	F1451NKGK
F1456NKGK	F1455NKGK8	F1455NKGI	F1451NKGI8
F1456NKGI8	F1455NKGK	F1451NKGK8	F1456NKGK8